



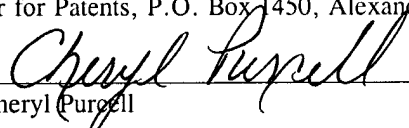
28358
DOCKET NO: VSEA 16-99

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Grant Kenji Larsen
Serial No: 09/676,548 ✓
Confirmation No: 2719
Filed: September 29, 2000
For: SURFACE STRUCUTRE AND METHOD OF MAKING, AND
ELECTROSTATIC WAFER CLAMP INCORPORATING
SURFACE STRUCTURE
Examiner: Stephen W. Jackson
Art Unit: 2836

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

The undersigned hereby certifies that this document is being placed in the United States mail with first-class postage attached, addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the 20th day of January, 2004.


Cheryl Purcell

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:
Transmitted herewith are the following documents:

- ☒ Ex Parte Quayle Response
- ☒ Petition for Extension of Time
- ☒ Terminal Disclaimer
- ☒ Return Receipt Postcard

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Please charge the terminal disclaimer fee of \$110.00 to Deposit Account 50-0896. If any additional fees are determined to be required or if there are any overpayments, Deposit Account 50-0896 may be charged or credited. A duplicate of this sheet is enclosed.

Respectfully submitted,
Grant Kenji Larsen, Applicant

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